

METHOD AND SYSTEM FOR
MANUFACTURING BALL GRID ARRAY ("BGA") PACKAGES

ABSTRACT OF THE DISCLOSURE

5 According to one embodiment of the invention, a method for manufacturing a ball grid array package includes providing a flip chip, coupling the flip chip to a first side of a substrate, encapsulating the flip chip with a molding, attaching a plurality of solder balls to a second side of the substrate, and cutting the substrate to produce the ball grid array package.